

Title (en)

Pattern forming device and pattern forming method

Title (de)

Musterbildende Vorrichtung und Verfahren zur Strukturbildung

Title (fr)

Dispositif et procédé de formation de motif

Publication

EP 2700737 A3 20150527 (EN)

Application

EP 13181003 A 20130820

Priority

JP 2012183261 A 20120822

Abstract (en)

[origin: EP2700737A2] A pattern forming device includes a plurality of tanks, and a power supply device. Each of the tanks has an open end having the same shape as a profile shape of a corresponding one of regions of a surface of a workpiece, in which different types of films are to be formed, and stores a corresponding one of electrodeposition solutions used to form the different types of films in a state where the open end is in contact with the surface. The power supply device applies a predetermined voltage to between the workpiece that serves as a first electrode, and each one of second electrodes in the tanks.

IPC 8 full level

C25D 5/02 (2006.01); **C25D 13/22** (2006.01); **C25D 17/00** (2006.01); **C25D 17/02** (2006.01); **C25D 17/12** (2006.01)

CPC (source: EP US)

C25D 5/02 (2013.01 - EP US); **C25D 13/22** (2013.01 - EP US); **C25D 17/00** (2013.01 - EP US); **C25D 17/02** (2013.01 - EP US); **C25D 17/12** (2013.01 - EP US); **C25D 17/004** (2013.01 - EP US)

Citation (search report)

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- [X] US 4315809 A 19820216 - PHILLIPS JAMES G
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Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

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DOCDB simple family (application)

EP 13181003 A 20130820; CN 201310361890 A 20130819; JP 2012183261 A 20120822; US 201313957865 A 20130802